MOSFET - N-Channel QFET®

600 V, 3.4 Ω, 3.0 A

FQP3N60C

General Description

This N-Channel enhancement mode power MOSFET is produced using ON Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 3.0 A, 600 V, $R_{DS(on)} = 3.4 \Omega$ (Max.) at $V_{GS} = 10 \text{ V}$, $I_D = 1.5 \text{ A}$
- Low Gate Charge (Typ. 10.5 nC)
- Low C_{rss} (Typ. 5.0 pF)
- 100% Avalanche Tested
- This is a Pb-Free Device

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter		Ratings	Unit
V _{DSS}	Drain-Source \	600	V	
V _{GSS}	Gate-Source V	±30	V	
I _D	Drain Current Continuous (T _C = 25°C)		3	Α
		Continuous (T _C = 100°C)	1.8	
I _{DM}	Drain Current	Pulsed (Note 1)	12	Α
E _{AS}	Single Pulse Av	150	mJ	
I _{AR}	Avalanche Curi	3	Α	
E _{AR}	Repetitive Aval	7.5	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5	V/ns
P _D	Power	(T _C = 25°C)	75	W
	Dissipation	Derate above 25°C	0.62	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		–55 to +150	°C
TL	Maximum Lead Soldering, 1/8"	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Repetitive rating: pulse-width limited by maximum junction temperature
- 2. L = 30 mH, I_{AS} = 3 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25 $^{\circ}$ C
- 3. $I_{SD} \le 3$ A, $di/dt \le 200$ A/ μ s, $V_{DD} \le BV_{DSS}$, starting $T_J = 25^{\circ}C$

THERMAL CHARACTERITICS

Symbol Parameter		Ratings	Unit
$R_{ heta JC}$	Maximum Thermal Resistance, Junction to Case	1.67	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	62.5	°C/W

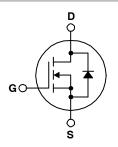
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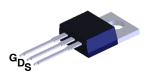
ON Semiconductor®

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V _{DS}	R _{DS(ON)} MAX	I _D MAX
600 V	3.4 Ω @ 10 V	3.0 A

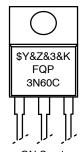


N-Channel MOSFET



TO-220-3LD CASE 340AT

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Data Code (Year & Week)

&K = Lot Code

FQP3N60C = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping
FQP3N60C	TO-220-3LD (Pb-Free)	50 Units/ Tube

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
OFF CHARA	ACTERISTICS			•	•	
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	600	_	-	V
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	_	0.6	_	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 600 V, V _{GS} = 0 V	-	-	1	μА
		V _{DS} = 480 V, T _C = 125 °C	-	-	10	
I _{GSSF}	Gate -Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	-	-	100	nA
I _{GSSR}	Gate -Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
ON CHARAC	CTERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.0	-	4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 1.5 A	-	2.8	3.4	Ω
9FS	Forward Transconductance	V _{DS} = 40 V, I _D = 1.5 A	-	3.5	-	S
YNAMIC C	HARACTERISTICS	•				-
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	-	435	565	pF
C _{oss}	Output Capacitance	1	-	45	60	pF
C _{rss}	Reverse Transfer Capacitance	7	-	5	8	pF
WITCHING	CHARACTERISTICS	•				-
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 300 \text{ V}, I_D = 3 \text{ A},$ $R_G = 25 \Omega$ (Note 4)	-	12	34	ns
t _r	Turn-On Rise Time		-	30	70	ns
t _{d(off)}	Turn-Off Delay Time		-	35	80	ns
t _f	Turn-Off Fall Time	7	-	35	80	ns
Qg	Total Gate Charge	V _{DS} = 480 V, I _D = 3 A, V _{GS} = 10 V	-	10.5	14	nC
Q _{gs}	Gate-Source Charge	(Note 4)	-	2.1	-	nC
Q _{gd}	Gate-Drain Charge	7	-	4.5	-	nC
RAIN-SOU	RCE DIODE CHARACTERISTICS AND MA	AXIMUM RATINGS				-
IS	Maximum Continuous Drain-Source Diod	le Forward Current	_	-	3	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-	-	12	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 3 A	-	-	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 3 A,	-	260	-	ns
Q _{rr}	Reverse Recovery Charge	dl _F /dt = 100 A/μs	-	1.6	-	μС

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature.

TYPICAL PERFORMANCE CHARACTERISTICS

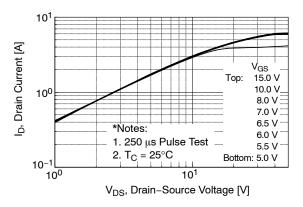


Figure 1. On-Region Characteristics

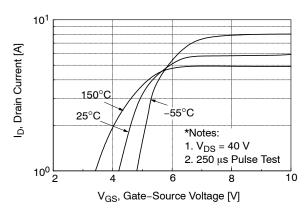


Figure 2. Transfer Characteristics

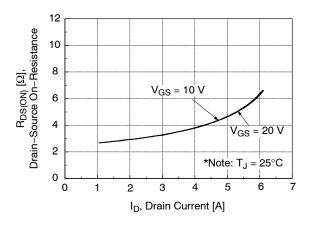


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

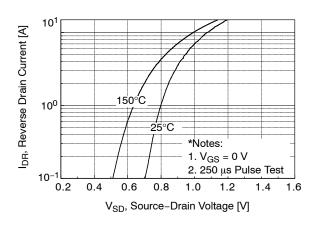


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

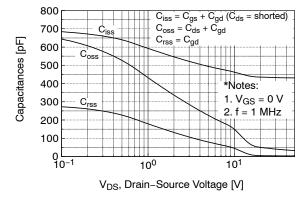


Figure 5. Capacitance Characteristics

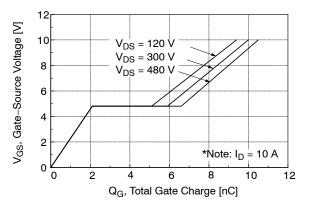


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS

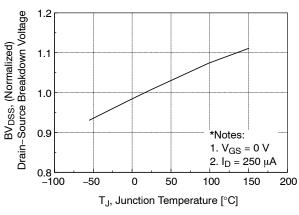


Figure 7. Breakdown Voltage Variation vs. Temperature

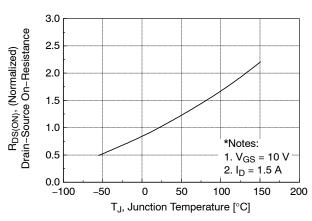


Figure 8. On–Resistance Variation vs.
Temperature

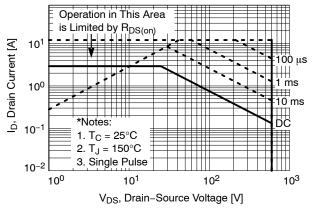


Figure 9. Maximum Safe Operating Area

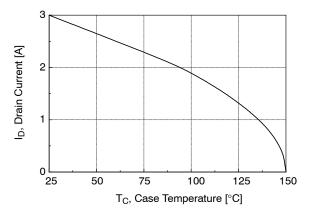


Figure 10. Maximum Drain Current vs. Case Temperature

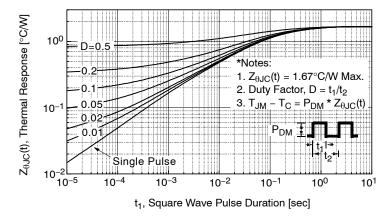


Figure 11. Transient Thermal Response Curve

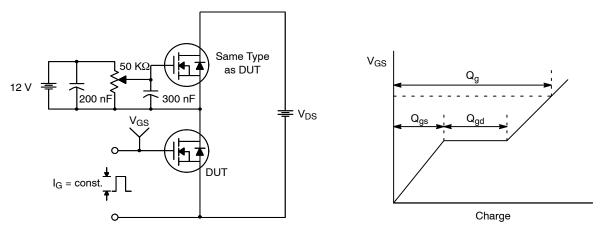


Figure 12. Gate Charge Test Circuit & Waveform

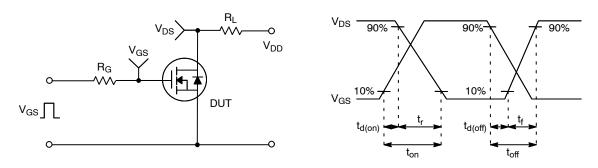


Figure 13. Resistive Switching Test Circuit & Waveforms

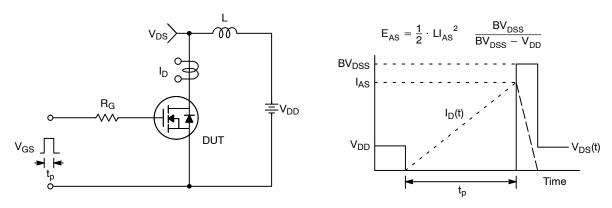


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

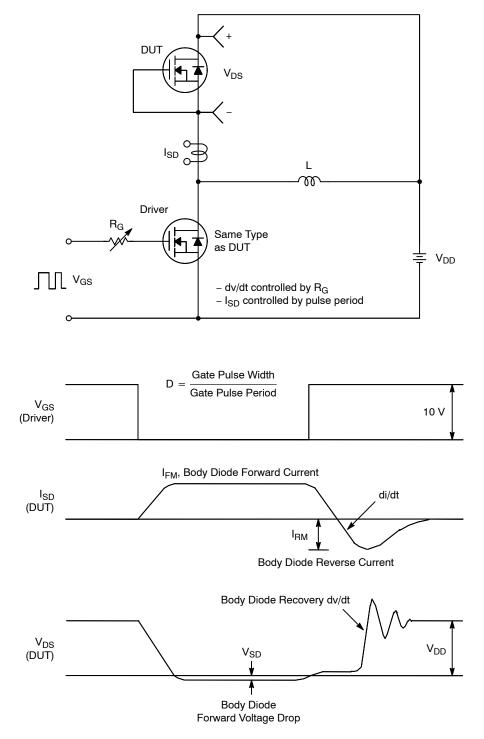
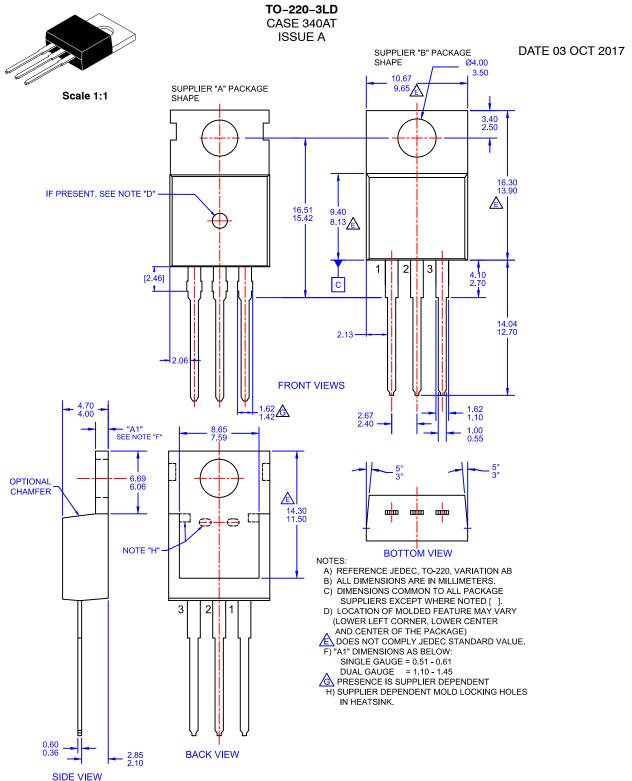


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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